

## **Technical implementation**

## **Products**

1- and 2-sided printed circuit boards Multilayer Flexible and rigid-flex printed circuits HDI/SBU technology HF printed circuit boards Metal core PCBs (IMS, MCS) Stretchable PCBs

Base material		Standard	Special**
Circuit board format (max.) [mm]		459 x 264	459 x 428
Base material		FR4, Polyimid	on request, high Tg, Rogers, IMS
Base material thickness for rigid		0,5 / 0,8 / 1,0 / 1,2 / 1,55 / 2,0 / 2,4	on request
single and double sided circuit boards [mm]		conform to IPC-4101 class B/L; 1,55 mm class M (±0,075 mm)	
Thickness rigid multilayer [mm] tolerance		0,5 - 3,2	on request
		Nominal dimension ±10%	Nominal dimension ±5%
Inner layer thicknesses [µm]		50 / 100 / 150 / 200 / 250 / 300 / 360 / 410 / 510 / 610 / 710	on request
Prepreg	thickness [μm] type	50 63 115 180 106 1080 2116 7628	on request
Thickness of flexible boards		Thickness of Polyimid (0.05 mm)	on request

Copper-thickness	Standard	Special**
Inner layer	18 μm, 35 μm	70 μm, 105 μm, on request
Outer layer (tolerance depends on layout)	35 μm	18 - 105 μm
In holes	≥20 μm	on request

Finish		Standard	Special**
Solder resist	Varnish	green	blue, red, black, yellow, white, amber, transparent; flexible varnish (green)
	Film		Polyimid Coverlay (with glue) Photoflex Coverlay (62 μm) Vacrel (75 μm)
Silk screen		white	yellow, green, blue, red, black
Finishing		ENIG; electroless tin; HAL lead free; OSP	ENEPIG; ISIG; HAL SnPb; electroplated gold; electroplated contact gold; Carbon; solder covering varnish

## **Special technologies**

Hole Plugging Cu-Micro-Via-Filling Stacked Vias

Layout guidelines		Standard	Special**
Smallest track width		125 μm	50 μm
Minimum track width		125 μm	50 μm
Padsize to hole diameter (pad annulus left after drilling) note: drilled hole diameter > finished diameter!	Outer layer:	≥ 100 µm	≥ 50 µm
	Inner layer:	≥ 125 µm	≥ 100 µm
	Clearance on internal layer:	≥ 200 µm	≥ 150 µm
Width residual tab solder mask (min.)		100 μm	60 μm
Stroke width assembly print (min.)		100 μm	75 μm

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Hole/Mill	Standard	Special**
Smallest hole finished diameter (TPH)	0,10 mm	0,05 mm
TPH aspect ratio (ratio of trough plated hole diameter to board thickness)	≥1:8	≥1:10
Blind via aspect ratio (ratio of blind via diameter to hole depth)	≥1:1	on request
Tolerance range of finished hole diameter (HAL)	0,15 mm (-0,05 mm/+0,10 mm)	0,10 mm
Tolerance of outer dimensions (milled)	DIN 7168-m, DIN ISO 2768-m	DIN 7168-f, DIN ISO 2768-f
Smallest milled radius	1,00 mm	0,40 mm

Offset	Standard	Special**
Milling to hole pattern	≤ 150 μm	≤ 100 µm
Milling to track pattern	≤ 150 μm	≤ 100 µm
Scoring to hole pattern	≤ 150 μm	≤ 100 µm
Holes	≤ 50 μm	≤ 50 μm
Holes (second clamping)	≤ 150 μm	≤ 100 µm
Hole pattern to track pattern	≤ 100 μm	≤ 50 μm
Track pattern to solder resist	≤ 75 μm	≤ 50 μm
Tolerance of residual tab by scoring	≤ 100 μm	≤ 75 µm

Standards	Standard	Special**
Test standard	IPC-A-600 Klasse II	As specified by customer
Controlled impedance	±10 %	±5 %
UL listed (Filenumber E228204)	UL94V-0; UL796	Material listing on request

\*\*according to prior agreement with CONTAG

The details given here relate to a standard job. For special circuit designs or requirements, other values may be needed as a basis. Please discuss your special requirements with our team, before placing an order (+49 30 351 788 - 300 or team@contag.de).

The manufacture of printed circuits is subject to continuous improvement, which then leads to additional technical options. This data sheet is thus regularly updated. If necessary, please request the latest edition.

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